PAL16L8AM, PAL16L8A-2M, PAL16R4AM, PAL16R4A-2M
PAL16R6AM, PAL16R6A-2M, PAL16R8AM, PAL16R8A-2M
STANDARD HIGH-SPEED *PAL*® CIRCUITS

- **Choice of Operating Speeds**
  High-Speed, A Devices . . . 25 MHz Min
  Half-Power, A-2 Devices . . . 16 MHz Min

- **Choice of Input/Output Configuration**

- **Package Options Include Both Ceramic DIP and Chip Carrier in Addition to Ceramic Flat Package**

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORTS
PAL16L8	10	2	0	6
PAL16R4	8	0	4 (3-state buffers)	4
PAL16R6	8	0	6 (3-state buffers)	2
PAL16R8	8	0	8 (3-state buffers)	0

PAL16L8'
J OR W PACKAGE

(TOP VIEW)

```
           ┌──────┐
    I  [ 1    20 ]  V_CC
    I  [ 2    19 ]  O
    I  [ 3    18 ]  I/O
    I  [ 4    17 ]  I/O
    I  [ 5    16 ]  I/O
    I  [ 6    15 ]  I/O
    I  [ 7    14 ]  I/O
    I  [ 8    13 ]  I/O
    I  [ 9    12 ]  O
  GND  [ 10    11 ]  I
           └──────┘
```
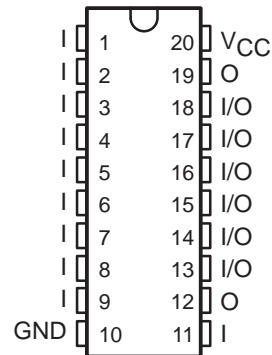
description

These programmable array logic devices feature high speed and a choice of either standard or half-power devices. They combine Advanced Low-Power Schottky technology with proven titanium-tungsten fuses. These devices will provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allow for quick design of "custom" functions and typically results in a more compact circuit board. In addition, chip carriers are available for further reduction in board space.

The Half-Power versions offer a choice of operating frequency, switching speeds, and power dissipation. In many cases, these Half-Power devices can result in significant power reduction from an overall system level.

The PAL16' M series is characterized for operation over the full military temperature range of $-55°C$ to $125°C$.
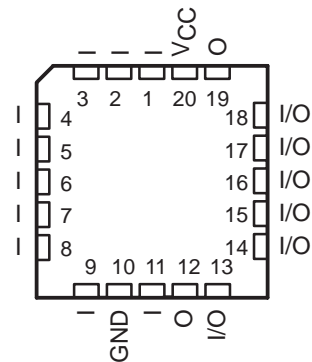
PAL16L8'
FK PACKAGE

(TOP VIEW)

```
          3  2  1  20 19
       ┌─────────────────┐
   I  [ 4              18 ]  I/O
   I  [ 5              17 ]  I/O
   I  [ 6              16 ]  I/O
   I  [ 7              15 ]  I/O
   I  [ 8              14 ]  I/O
       └─────────────────┘
          9  10 11 12 13
```

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PAL16R4AM, PAL16R4A-2M, PAL16R6AM, PAL16R6A-2M, PAL16R8AM, PAL16R8A-2M
STANDARD HIGH-SPEED *PAL*® CIRCUITS

PAL16R4'
J OR W PACKAGE

(TOP VIEW)

CLK	1		20	V_{CC}
I	2		19	I/O
I	3		18	I/O
I	4		17	Q
I	5		16	Q
I	6		15	Q
I	7		14	Q
I	8		13	I/O
I	9		12	I/O
GND	10		11	$\overline{OE}$
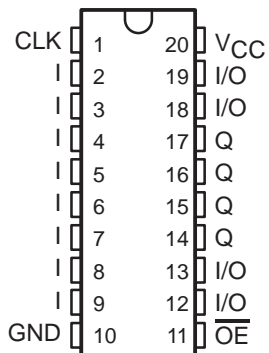
PAL16R4'
FK PACKAGE

(TOP VIEW)
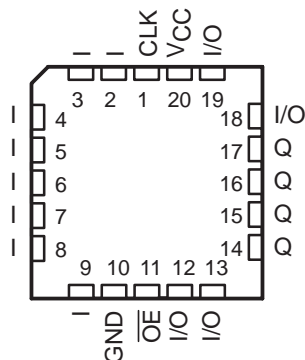
PAL16R6'
J OR W PACKAGE

(TOP VIEW)

CLK	1		20	V_{CC}
I	2		19	I/O
I	3		18	Q
I	4		17	Q
I	5		16	Q
I	6		15	Q
I	7		14	Q
I	8		13	Q
I	9		12	I/O
GND	10		11	$\overline{OE}$
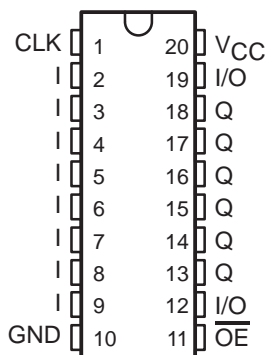
PAL16R6'
FK PACKAGE

(TOP VIEW)
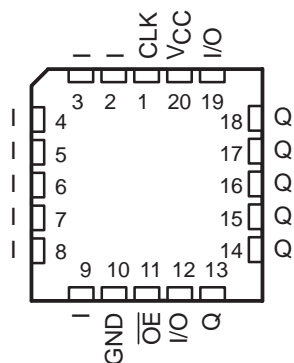
PAL16R8'
J OR W PACKAGE

(TOP VIEW)

CLK	1		20	V_{CC}
I	2		19	Q
I	3		18	Q
I	4		17	Q
I	5		16	Q
I	6		15	Q
I	7		14	Q
I	8		13	Q
I	9		12	Q
GND	10		11	$\overline{OE}$
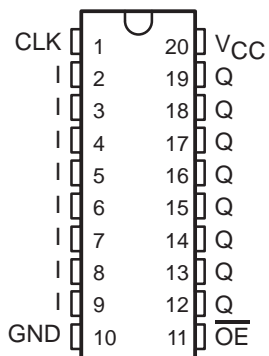
PAL16R8'
FK PACKAGE

(TOP VIEW)

TEXAS
INSTRUMENTS

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functional block diagrams (positive logic)

PAL16L8AM
PAL16L8A-2M

PAL16R4AM
PAL16R4A-2M

∿ denotes fused inputs

functional block diagrams (positive logic)

PAL16R6AM
PAL16R6A-2M

PAL16R8AM
PAL16R8A-2M

∿ denotes fused inputs

logic diagram (positive logic)

Fuse number = First fuse number + Increment
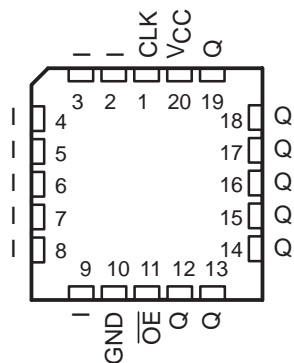
PAL16R4AM, PAL16R4A-2M
STANDARD HIGH-SPEED *PAL*® CIRCUITS

logic diagram (positive logic)
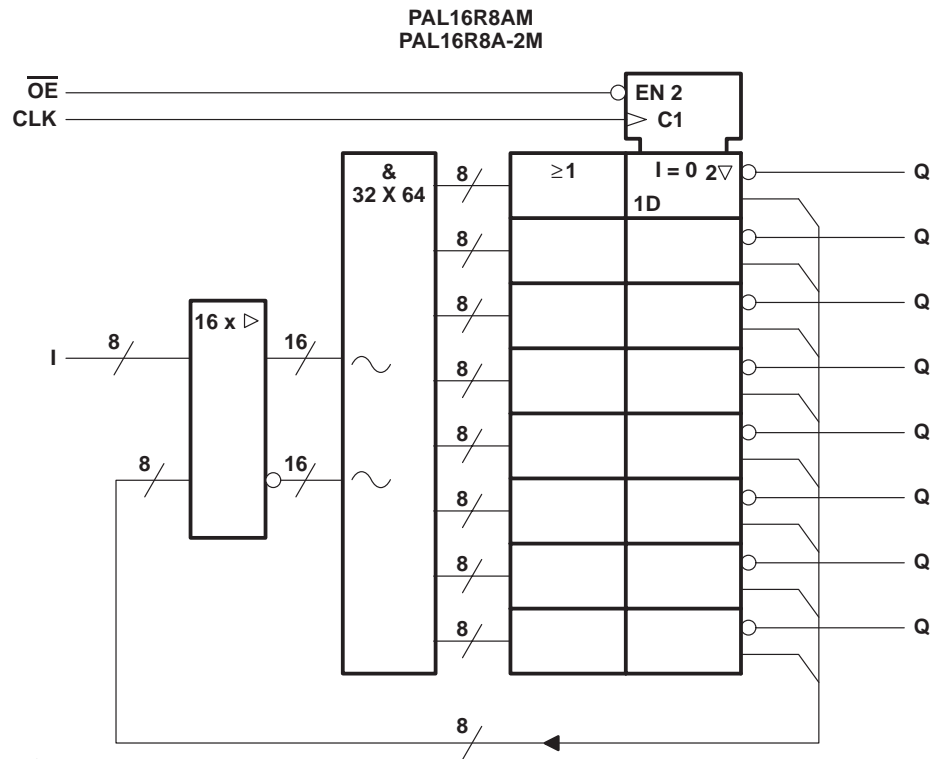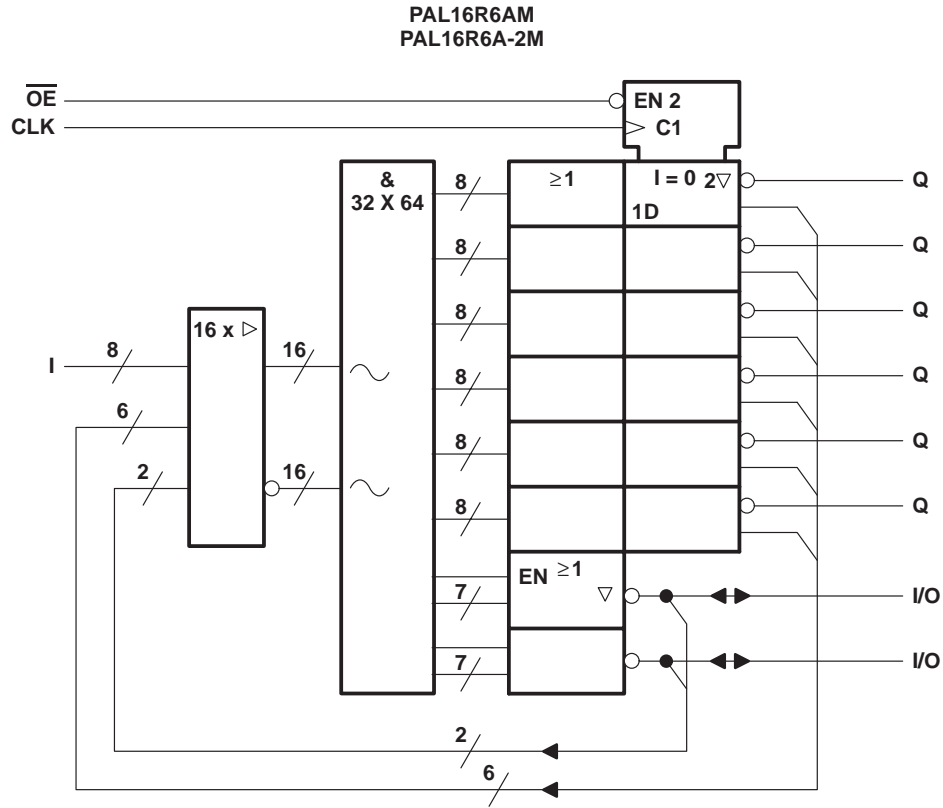
Fuse number = First fuse number + Increment

TEXAS
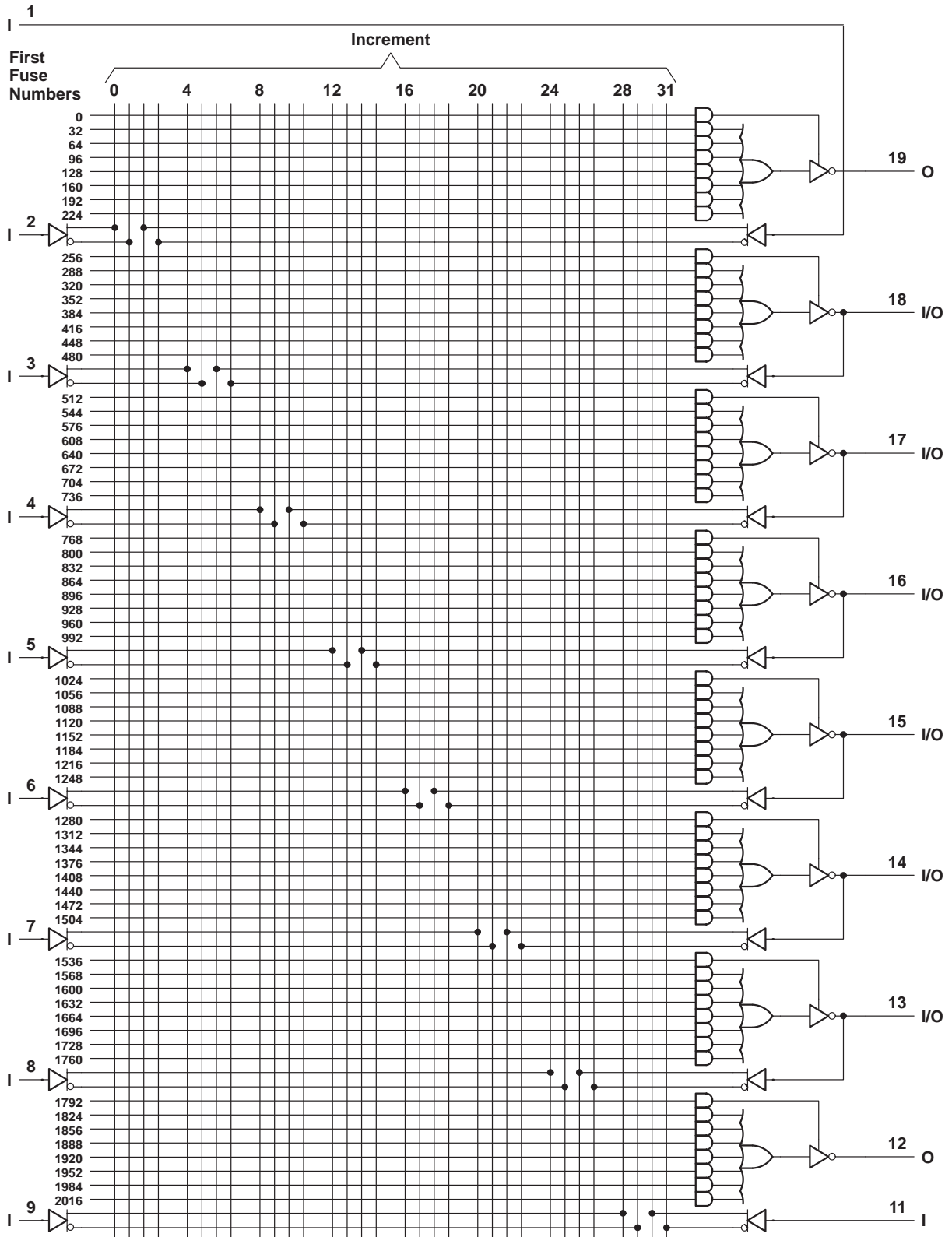INSTRUMENTS

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logic diagram (positive logic)

Fuse number = First fuse number + Increment
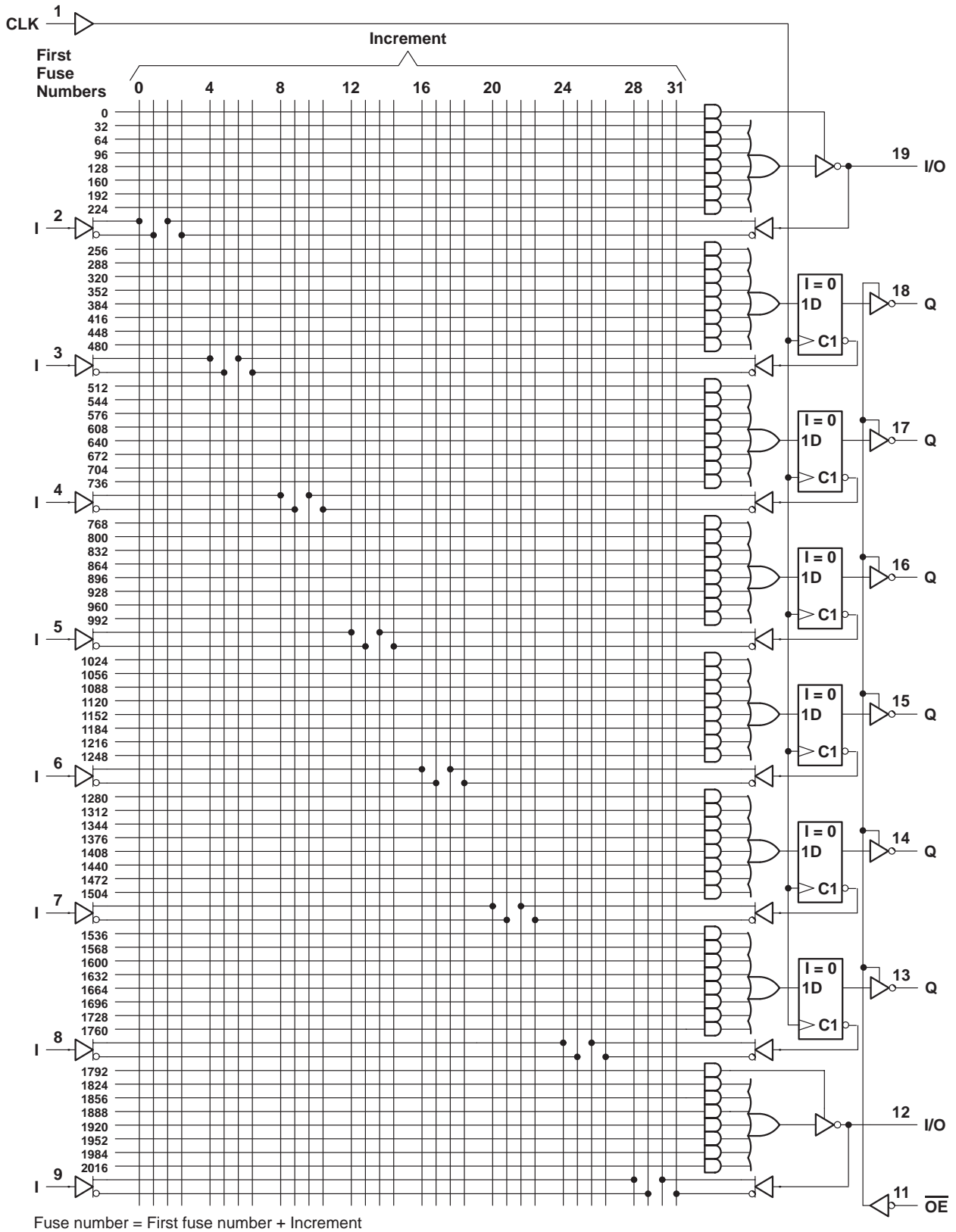
logic diagram (positive logic)

Fuse number = First fuse number + Increment
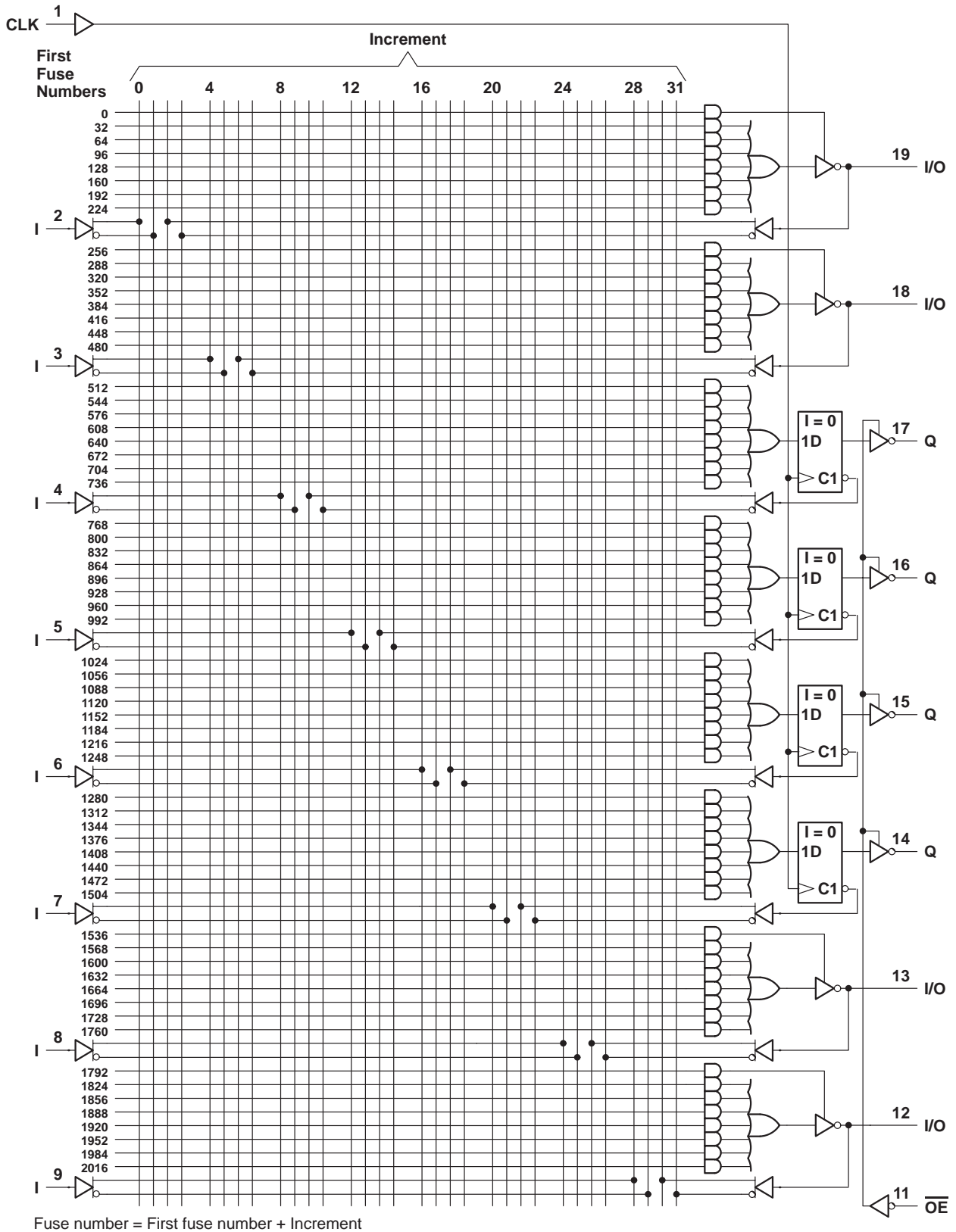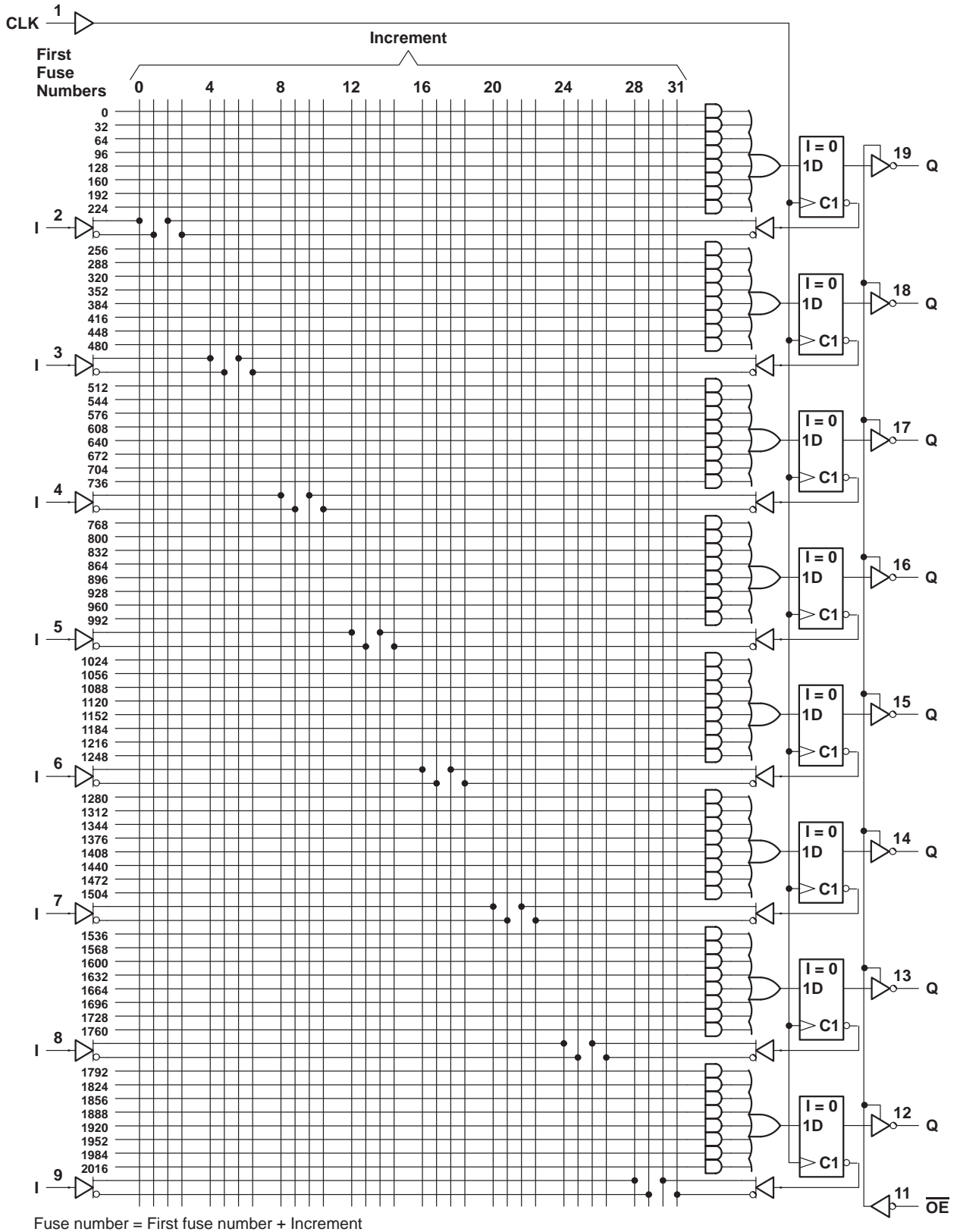
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programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage (see Note 1) . . . . 5.5 V
Voltage applied to disabled output (see Note 1) . . . . 5.5 V
Operating free-air temperature range . . . . −55°C to 125°C
Storage temperature range . . . . −65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2		5.5	V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			−2	mA
I_{OL}	Low-level output current			12	mA
T_A	Operating free-air temperature	−55	25	125	°C

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA				−1.5	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = −2 mA		2.4	3.2		V
V_{OL}		V_{CC} = 4.5 V,	I_{OL} = 12 mA			0.25	0.4	V
I_{OZH}	Outputs	V_{CC} = 5.5 V,	V_O = 2.7 V				20	µA
	I/O ports						100	
I_{OZL}	Outputs	V_{CC} = 5.5 V,	V_O = 0.4 V				−20	µA
	I/O ports						−100	
I_I		V_{CC} = 5.5 V,	V_I = 5.5 V				0.2	mA
I_{IH}	I/O Ports	V_{CC} = 5.5 V,	V_I = 2.7 V				100	µA
	All others						25	
I_{IL}	$\overline{OE}$ input	V_{CC} = 5.5 V,	V_I = 0.4 V				−0.2	mA
	All others						−0.1	
I_{OS}‡		V_{CC} = 5.5 V,	V_O = 0.5 V		−30		−250	mA
I_{CC}		V_{CC} = 5.5 V,	V_I = 0,	Outputs open		75	180	mA

timing requirements

			MIN	MAX	UNIT
f_{clock}	Clock Frequency		0	25	MHz
t_w	Pulse duration (see Note 2)	Clock high	15		ns
		Clock low	20		
t_{su}	Setup time, input or feedback before CLK↑		25		ns
t_h	Hold time, input or feedback after CLK↑		0		ns

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock}. The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	TYP†	MAX	UNIT
f_{max}				25	45		MHz
t_{pd}	I, I/O	O, I/O			15	30	ns
t_{pd}	CLK↑	Q	R1 = 390 Ω,		10	20	ns
t_{en}	$\overline{OE}$↓	Q	R2 = 750 Ω,		15	25	ns
t_{dis}	$\overline{OE}$↑	Q	See Figure 1		10	25	ns
t_{en}	I, I/O	O, I/O			14	30	ns
t_{dis}	I, I/O	O, I/O			13	30	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IK}		$V_{CC} = 4.5$ V,	$I_I = -18$ mA				−1.5	V
V_{OH}		$V_{CC} = 4.5$ V,	$I_{OH} = -2$ mA		2.4	3.2		V
V_{OL}		$V_{CC} = 4.5$ V,	$I_{OL} = 12$ mA			0.25	0.4	V
I_{OZH}	Outputs	$V_{CC} = 5.5$ V,	$V_O = 2.7$ V				20	μA
	I/O ports						100	
I_{OZL}	Outputs	$V_{CC} = 5.5$ V,	$V_O = 0.4$ V				−20	μA
	I/O ports						−100	
I_I		$V_{CC} = 5.5$ V,	$V_I = 5.5$ V				0.2	mA
I_{IH}	I/O Ports	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V				100	μA
	All others						25	
I_{IL}	$\overline{OE}$ input	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V				−0.2	mA
	All others						−0.1	
I_{OS}‡		$V_{CC} = 5.5$ V,	$V_O = 0.5$ V		−30		−250	mA
I_{CC}		$V_{CC} = 5.5$ V,	$V_I = 0$,	Outputs open		75	90	mA

timing requirements

			MIN	MAX	UNIT
f_{clock}	Clock Frequency		0	16	MHz
t_w	Pulse duration (see Note 2)	Clock high	25		ns
		Clock low	25		
t_{su}	Setup time, input or feedback before CLK↑		35		ns
t_h	Hold time, input or feedback after CLK↑		0		ns

NOTE 2: The total clock period of clock high and clock low must not exceed clock frequency, f_{clock}. The minimum pulse durations specified are only for clock high or low, but not for both simultaneously.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	TYP†	MAX	UNIT
f_{max}				16	25		MHz
t_{pd}	I, I/O	O, I/O			25	40	ns
t_{pd}	CLK↑	Q	$R1 = 390$ Ω,		11	25	ns
t_{en}	$\overline{OE}$↓	Q	$R2 = 750$ Ω,		20	25	ns
t_{dis}	$\overline{OE}$↑	Q	See Figure 1		11	25	ns
t_{en}	I, I/O	O, I/O			25	40	ns
t_{dis}	I, I/O	O, I/O			25	35	ns

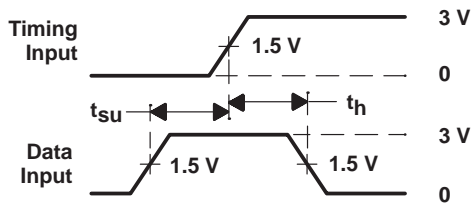† All typical values are at $V_{CC} = 5$ V, $T_A = 25$°C.
‡ Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second. Set V_O at 0.5 V to avoid test equipment degradation.
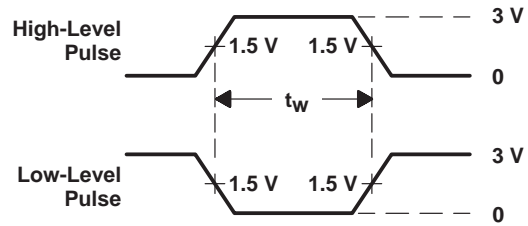
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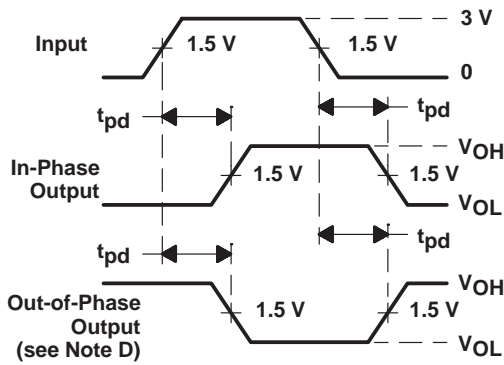## PARAMETER MEASUREMENT INFORMATION
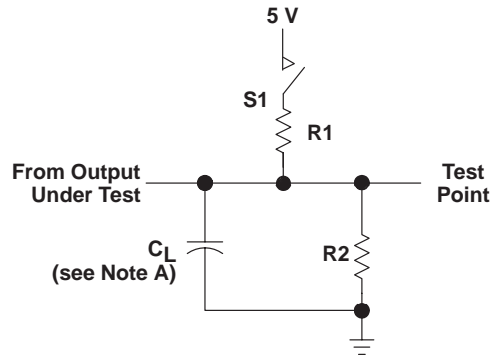
**LOAD CIRCUIT FOR
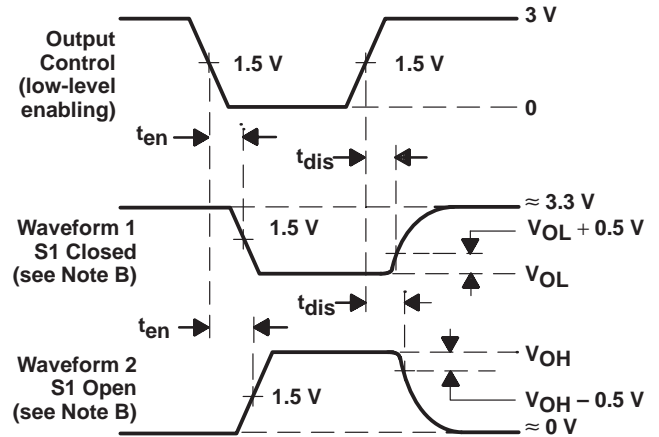3-STATE OUTPUTS**

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS
PULSE DURATIONS**

**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES**

**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS**

NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en}, 5 pF for t_{dis}.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses have the following characteristics: PRR ≤ 10 MHz, t_r and t_f ≤ 2 ns, duty cycle = 50%
D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
E. Equivalent loads may be used for testing.

Figure 1. Load Circuit and Voltage Waveforms

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